

Jetson Orin Nano Developer Kit Carrier Board

Specification

Document History

SP-11324-001_v1.1

Version	Date	Description of Change		
1.0	March 20, 2023	Initial release		
1.1	May 17, 2023	Updated Note in Chapter 1: Introduction with VDD_IN related information.		
		 Updated Pin #13 in Table 2-5: DisplayPort Connector Pin Description – J8. 		
		 Updated Pin #55 and Pin #57 in Table 2-6: M.2 Key E Expansion Slot Pin Description – J10. 		
		> Added developer kit weight.		
		> Updated Figure 5-1: Power Diagram.		
		> Updated VDD_5V_SYS in Table 5-2: Interface Supply Current Capabilities.		
		 Updated Table 5-3: Supply Current Capabilities per Connector per Supply; replaced VDD_IN with VDD_5V_SYS. 		

Table of Contents

Chapter	1. Introduction	1
1.1	Jetson Orin Nano Module Feature List	2
1.2	Carrier Board Feature List	2
1.3	Jetson Orin Nano Carrier Board Block Diagram	3
Chapter	2. Jetson Nano Carrier Board Standard Connectors	7
2.1	USB Ports	7
2.2	Gigabit Ethernet	10
2.3	DisplayPort	11
2.4	M.2 Key E Expansion Slot	12
2.5	M.2 Key M Expansion Slot	14
Chapter	3. Carrier Board Custom Expansion IF Connections	18
3.1	Jetson Orin Nano Module Connector	18
3.2	Camera Connector	18
3.3	40-Pin Expansion Header	21
3.4	Button Header	24
3.5	Optional CAN Bus Header	25
3.6	Fan Connector	25
3.7	Optional Battery Back-up Coin Cell Holder	26
3.8	DC Power Jack	26
3.9	Optional Power-Over Ethernet and Backpower Headers	27
Chapter	4. Mechanical Specification	29
Chapter	5. Interface Power	31

List of Figures

Figure 1-1.	Jetson Orin Nano Block Diagram	4
Figure 1-2.	Jetson Orin Nano – Top View (Envelope)	4
Figure 1-3.	Jetson Orin Nano – Bottom View (Envelope)	
Figure 1-4.	Jetson Orin Nano Carrier Board Placement – Top View	5
Figure 1-5.	Jetson Orin Nano Carrier Board Placement – Bottom View	
Figure 3-1.	Expansion Header Connections	21
Figure 3-2.	Jack Connector	26
Figure 3-3.	PoE Alternative Power Input	27
Figure 4-1.	Developer Kit Carrier Board Mechanical Dimensions	29
Figure 4-2.	Developer Kit Mechanical Dimensions	30
Figure 5-1.	Power Diagram	
List of 7	Tables	
Table 2-1.	USB 3.2 Type C Connector Pin Description – J5	7
Table 2-2.	USB 3.2 Type A Connector Pin Descriptions – J6	8
Table 2-3.	USB 3.2 Type A Connector Pin Description – J7	9
Table 2-4.	Ethernet RJ45 Connector Pin Description - J15	10
Table 2-5.	DisplayPort Connector Pin Description - J8	11
Table 2-6.	M.2 Key E Expansion Slot Pin Description - J10	12
Table 2-7.	M.2 Key M Expansion Slot Pin Description - J11 (x4 PCIe)	14
Table 2-8.	M.2 Key M Expansion Slot Pin Description – J24 (x2 PCIe)	16
Table 3-1.	Camera #0 Connector Pin Description – J20	19
Table 3-2.	Camera #1 Connector Pin Description - J21	20
Table 3-3.	Expansion Header Pin Description – J12	22
Table 3-4.	Button Header Description - J14	24
Table 3-5.	Optional CAN Header Pin Description – J17	25
Table 3-6.	Fan Connector Pin Description - J13	25
Table 3-7.	RTC Backup Batter Connector Pin Description – J3	26
Table 3-8.	DC Jack Pin Description – J16	27
Table 3-9.	PoE Header – J19	27
Table 3-10.	PoE Backpower Header – J18	28
Table 5-1.	Interface Power Supply Allocation	32
Table 5-2.	Interface Supply Current Capabilities	32
Table 5-3.	Supply Current Capabilities per Connector per Supply	33

Chapter 1. Introduction

This specification contains recommendations and guidelines for engineers to follow to create modules for the expansion connectors on the NVIDIA® Jetson Orin™ Nano carrier board. As well as understand the capabilities of the other dedicated interface connectors and associated power solutions on the platform.

The Jetson Orin Nano carrier board is ideal for software development within the Linux environment. Standard connectors are used to access Jetson Orin Nano features and interfaces, enabling a highly flexible and extensible development platform. Go to https://developer.nvidia.com/embedded/develop or r contact your NVIDIA representative for access to software updates and the developer SDK supporting the OS image and host development platform that you want to use. The developer SDK includes an OS image that you will load onto your Jetson Orin Nano device, supporting documentation, and code samples to help you get started.

The Jetson Orin Nano carrier board supports all the Jetson Orin Nano Series and Jetson Orin NX Series modules.



Caution: ALWAYS CONNECT JETSON ORIN NANO and ALL EXTERNAL PERIPHERAL DEVICES BEFORE CONNECTING THE POWER SUPPLY TO THE AC POWER JACK. Connecting a device while powered on may damage the developer kit carrier board, Jetson Orin Nano, or peripheral device. In addition, the carrier board should be powered down and the power removed before plugging or unplugging devices or add-on modules into the headers. Wait for the red power VDD IN LED to turn off or wait for 5 minutes if your system does not have a power LED. This includes the Jetson Orin Nano module, the camera connector, the M.2 connector, and the other expansion headers.

The Jetson Orin Nano developer board contains ESD-sensitive parts. Always use appropriate anti-static and grounding techniques when working with the system. Failure to do so can result in ESD discharge to sensitive pins, and irreparably damage your Jetson Orin Nano board. NVIDIA will not replace units that have been damaged due to ESD discharge.



Note: The developer kit carrier board has been modified to only support 5V to the module. The MODULE_ID signal is not pulled up on the carrier board. This means that regardless of the capability of the module, VDD_IN will be 5V only. Custom carrier boards can still be designed to support 5V and 19V and use the MODULE_ID to identify a 5V vs. 19V Input. Orin NX can still operate up to the full 20W-25W with the 5V VDD_IN.

1.1 Jetson Orin Nano Module Feature List

The following is a list of features for the Jetson Orin Nano module.

- > Applications processor (AP)
 - NVIDIA Orin™
- > Memory
 - 8 GB 128-bit wide LPDDR5 DRAM (68 GB/s)
 - Micro SD card socket (UHS-1)
- > Networking
 - 10/100/1000 BASE-T Ethernet
- Advanced power management (APM)
- > Dynamic voltage and frequency scaling
- > Multiple clock and power domains

Carrier Board Feature List 1.2

The following is a list of features for the carrier board.

- > Connection to Jetson Orin Nano
 - 260-pin SO-DIMM connector
- > USB
 - USBC: Supports Recovery Mode
 - USB 3.2 (Gen2x1) Hub to 4x Type A (host only)
- > Wired network
 - Gigabit Ethernet (RJ45 connector with LEDs and optional PoE header)
- > Display
 - VESA® DisplayPort™ (DP v1.2 (+MST) and eDP v1.4)
- > Camera connectors
 - 2x 22-position flex connectors
 - CSI (2.5 Gbps per pair): 1, x2 or x4 and 1, x2
 - Camera CLK, I2C, and control
- > M.2 Key E connector
 - PCIe (Gen3) x1 Lane, USB 2.0
 - I2S, UART, I2C
 - Control

- > M.2 Key M connector (x2)
 - #1) PCIe (Gen3) x4 lane, control
 - #2) PCIe (Gen3) x2 lane, control
- > Expansion header
 - 40-pin (2x20) header
 - I2C (x2), SPI (x2), UART
 - I2S, audio clock, GPIOs, PWMs
- UI and indicators
 - Button header: Power, reset, force recovery, debug UART, Auto-Power-On disable
 - LEDs: Power
- > Miscellaneous
 - Fan connector: 5V, PWM, and tach
 - Optional RTC back-up connector
 - Optional CAN header
- Power
 - DC Jack: 9-20 V (19V supply provided)
 - Optional Ethernet PoE and back power headers
 - Main 5.0 V Pre-regulator: GS9230 (or A0Z2264)
 - Provides VDD_IN to module
 - Main 3.3V supply: GS9230 (or A0Z2264)
 - Main 1.8V supply: GS7116S5
 - 3.3V AO (always on) supply: GS7116S5
 - USB VBUS load switches: AP22811AW5-7 (x2)
 - DP 3.3V power switch: APL3552ABI-TRG
- Developer kit operating temperature range
 - 0°C to 35°C

Jetson Orin Nano Carrier Board Block 1.3 Diagram

Figure 1-1 through Figure 1-5 show the block diagram and various placement views for Jetson Orin Nano and the carrier board.

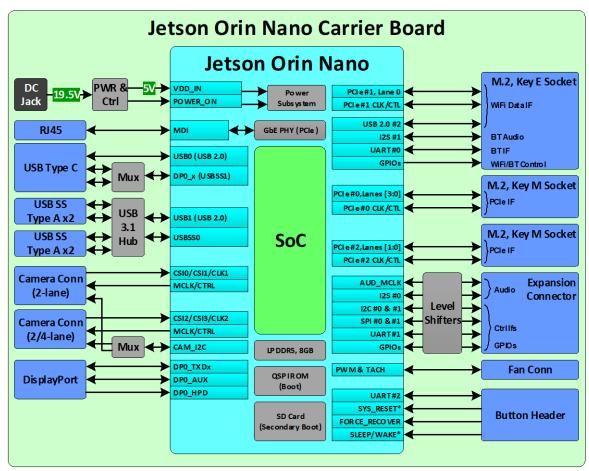
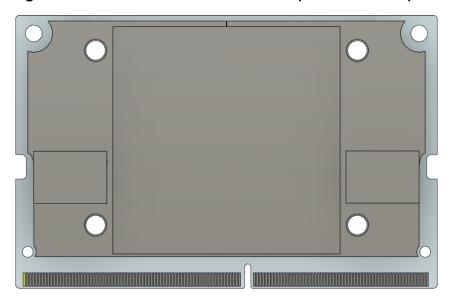


Figure 1-1. Jetson Orin Nano Block Diagram





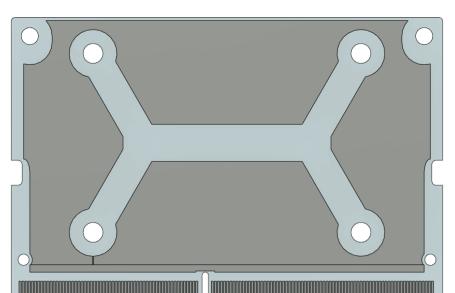
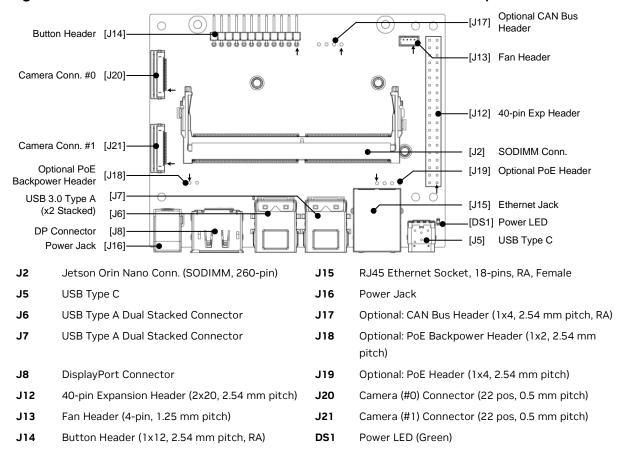


Figure 1-3. Jetson Orin Nano - Bottom View (Envelope)





 \bigcirc \bigcirc 00 0 0 M.2, Key E [J10]-Socket M.2, Key M (0) [J24] Socket (2-lane) M.2, Key M (0) Socket (4-lane) 00 Optional RTC Battery Connector J3 Optional: RTC Back-up Coin Cell Socket (CR1225)

Figure 1-5. Jetson Orin Nano Carrier Board Placement - Bottom View

- J11 M.2 Key M Slot (75-pin)
- M.2 Key E Connectivity Slot (75-pin) J10
- **J24** M.2 Key M Slot (75-pin)

Chapter 2. Jetson Nano Carrier Board Standard Connectors

The Jetson Orin Nano carrier board provides several connectors with industry standard pinouts to support additional functionality beyond what is integrated on the main platform board. This includes:

- > USB 3.2: Type C connector
- USB 3.2: 2 x Type A stacked connectors
- > Gigabit Ethernet: RJ45 connector
- > DisplayPort connector
- > M.2, Key E socket
- > M.2, Key M socket (4-lane PCle)
- > M.2, Key M socket (2-lane PCle)

2.1 **USB Ports**

The carrier board supports five USB connectors. One is a USB 3.2 Type C connector (J5) supporting host, device, and USB Recovery. In addition, there are two, dual stacked USB 3.2 Type A connectors (J6 and J7). Each connector supports host mode only. A load switch supplying VBUS is provided for each of the USB 3.2 ports per stack and is limited to 3A of output current.

Table 2-1. USB 3.2 Type C Connector Pin Description – J5

Pin#	Connector Pin Name	Associated Module Pin Name (See Note 1 and 2)	Module Pin #	Usage/Description	Type/Dir
A1	GND_A	_	_	Ground	Ground
A2	TX1_P	USBSS1_TX_P	G23	USB 3.2 #1 Transmit 1 from	
А3	TX1_N	USBSS1_TX_N	G22	mux	
A4	-	_	_	USB VBUS_A Power	Power
A5	CC1	-	_	CC 1 from CC Controller	Output
A6	D1_P	USB0_D_P	F12	USB 2.0 #0 Data 1	Bidir

Pin#	Connector Pin Name	Associated Module Pin Name (See Note 1 and 2)	Module Pin #	Usage/Description	Type/Dir
A7	D1_N	USB0_D_N	F13		
A8	SBU1	_	_	Unconnected	_
A9	_	-	_	USB VBUS_A Power	Power
A10	RX2_N	USBSS1_RX_P	C22	USB 3.2 #1 Receive 2 from	la a vet
A11	RX2_P	USBSS1_RX_N	C23	mux	Input
A12	GND_A	_	_	Ground	Ground
В1	GND_B	_	_	Ground	Ground
B2	TX2_P	USBSS1_TX_P	G23	USB 3.2 #1 Transmit 2 from	O otor ot
В3	TX2_N	USBSS1_TX_N	G22	mux	Output
B4	_	-	_	USB VBUS_A Power	Power
B5	CC2	_	_	CC 2 from CC Controller	Output
В6	D2_P	USB0_D_P	F12	110D 0 0 110 D 1 0	D: 1:
В7	D2_N	USB0_D_N	F13	USB 2.0 #0 Data 2	Bidir
B8	SBU2	-	_	Unconnected	-
В9	-	-	_	USB VBUS_A Power	Power
B10	RX1_N	USBSS1_RX_P	C22	USB 3.2 #1 Receive 1 from	
B11	RX1_P	USBSS1_RX_N	C23	mux	Input
B12	GND_B	-	_	Ground	Ground

- 1. USB 3.2 module pin names are using the Orin NX and Orin Nano function names.
- $2. \ The \ module \ pins \ for \ the \ USB \ 3.2 \ ports \ are \ not \ directly \ connected \ to \ the \ USB \ connector \ pins \ but \ are \ routed$ through a multiplexer.
- 3. In the Type/Dir column, Output is to USB connectors. Input is from USB connectors. Bidir is for bidirectional signals.

Legend	Ground	Power	Reserved
Legena	Ground	rowei	Reserveu

USB 3.2 Type A Connector Pin Descriptions - J6 Table 2-2.

Pin#	Module Pin Name (see Note 1 and 2)	Module Pin #	Usage/Description	Type/Dir
USB 3.0	Туре А (2)			
1	-	-	VBUS Supply	Power
2	USB1_D_N			
3	USB1_D_P	USB 2.0 #2 Data from hub		Bidir
4	-	-	Ground	Ground
5	USBSSO_RX_N	161	USB 3.1 Receive #2 Data from hub	Input

Pin#	Module Pin Name (see Note 1 and 2)	Module Pin #	Usage/Description	Type/Dir	
6	USBSSO_RX_P	163			
7	_	_	Ground	Ground	
8	USBSSO_TX_N	166			
9	USBSS0_TX_P	168	USB 3.1 Transmit #2 Data from hub	Output	
USB 3.0	USB 3.0 Type A (1)				
10	-	-	VBUS Supply	Power	
11	USB1_D_N	115		D. I.	
12	USB1_D_P	117	USB 2.0 Data #1 Data from hub	Bidir	
13	-	-	Ground	Ground	
14	USBSSO_RX_N	161			
15	USBSSO_RX_P	163	USB 3.1 Receive #1 Data from hub	Input	
16	-	_	Ground	Ground	
17	USBSSO_TX_N	166			
18	USBSS0_TX_P	168	USB 3.1 Transmit #1 Data from hub	Output	

- 1. USB 3.2 module pin names are using the Orin NX and Orin Nano function names.
- 2. The module pin names not directly connected to the USB connector pins but are routed to the input of the USB hub.
- 3. In the Type/Dir column, Output is to USB connectors. Input is from USB connectors. Bidir is for bidirectional signals.

Legeria Ground Power Reserved	Legend	Ground	Power	Reserved
-------------------------------	--------	--------	-------	----------

USB 3.2 Type A Connector Pin Description - J7 Table 2-3.

Pin#	Module Pin Name (see Note 1 and 2)	Module Pin #	Usage/Description	Type/Dir			
USB 3.0 T	JSB 3.0 Type A (2)						
1	_	_	VBUS Supply	Power			
2	USB1_D_N	115	UCD 20 #4 Data from hub	Didia			
3	USB1_D_P	117	USB 2.0 #4 Data from hub	Bidir			
4	_	_	Ground	Ground			
5	USBSSO_RX_N	161	UCD 2.1 Descive #4 Data from hub	la a de			
6	USBSSO_RX_P	163	USB 3.1 Receive #4 Data from hub	Input			
7	_	_	Ground	Ground			
8	USBSSO_TX_N	166	UCD 2.1 Transmit #4 Data from hub	Output			
9	USBSS0_TX_P	168	USB 3.1 Transmit #4 Data from hub	Output			

Pin#	Module Pin Name (see Note 1 and 2)	Module Pin #	Usage/Description	Type/Dir			
USB 3.0	JSB 3.0 Type A (1)						
10	-	_	VBUS Supply	Power			
11	USB1_D_N	115	11CD 2 0 Data #2 Data francis bulk	Di di			
12	USB1_D_P	117	USB 2.0 Data #3 Data from hub	Bidir			
13	_	_	Ground	Ground			
14	USBSSO_RX_N	161	UCD 2.1 Dansing #2 Data from hole	l t			
15	USBSSO_RX_P	163	USB 3.1 Receive #3 Data from hub	Input			
16	_	_	Ground	Ground			
17	USBSS0_TX_N	166	U0D 0.1 T 1/10 D (1 1				
18	USBSS0_TX_P	168	USB 3.1 Transmit #3 Data from hub	Output			

- 1. USB 3.2 module pin names are using the Orin NX and Orin Nano function names.
- 2. The module pin names not directly connected to the USB connector pins but are routed to the input of the USB hub.
- 3. In the Type/Dir column, Output is to USB connectors. Input is from USB connectors. Bidir is for bidirectional signals.

L egend Ground	Power	Reserved
-----------------------	-------	----------

Gigabit Ethernet

The carrier board implements an RJ45 connector (J15) along with the necessary magnetics device.

Table 2-4. Ethernet RJ45 Connector Pin Description - J15

Pin#	Module Pin Name	Module Pin #	Usage/Description	Type/Dir
1	GPE_MDI0_P	186	Gigabit Ethernet MDI 0+	Bidir
2	GPE_MDI0_N	184	Gigabit Ethernet MDI 0-	Bidir
3	GPE_MDI1_P	192	Gigabit Ethernet MDI 1+	Bidir
4	_	-	мст	_
5	_	-	мст	_
6	GPE_MDI1_N	190	Gigabit Ethernet MDI 1-	Bidir
7	GPE_MDI2_P	198	Gigabit Ethernet MDI 2+	Bidir
8	GPE_MDI2_N	196	Gigabit Ethernet MDI 2-	Bidir
9	GPE_MDI3_P	204	Gigabit Ethernet MDI 3+	Bidir

Pin#	Module Pin Name	Module Pin #	Usage/Description	Type/Dir
10	GPE_MDI3_N	202	Gigabit Ethernet MDI 3-	Bidir
11				
12				_
13	_	-	Power-Over-Ethernet	Power
14				
15	_	_	Green LED Anode	Input
16	GBE_LED_LINK	188	Green LED Cathode. On for 1,000 Mbps link. Off for 10/100Mbps.	Output
17	_	_	Yellow LED Anode	Input
18	GBE_LED_ACT	194	Yellow LED Cathode. On indicates activity.	Output
19				
20	_	-	Shield Ground	Ground

Note: In the Type/Dir column, Output is to RJ45 connector. Input is from RJ45 connector. Bidir is for bidirectional signals.

Legend Ground	Power	Reserved
---------------	-------	----------

2.3 DisplayPort

A DisplayPort (DP) connector (J8) is provided. Dual mode is supported.

DisplayPort Connector Pin Description - J8 Table 2-5.

Pin#	Module Pin Name	Module Pin #	Usage/Description	Type/Dir
1	DP0_TXD0_P	41	DP Lane 0+	Output
2	_	-	Ground	Ground
3	DP0_TXD0_N	39	DP Lane 0-	Output
4	DP0_TXD1_P	47	DP Lane 1+	Output
5	_	-	Ground	Ground
6	DP0_TXD1_N	45	DP Lane 1-	Output
7	DP0_TXD2_P	53	DP Lane 2+	Output
8	_	_	Ground	Ground
9	DP0_TXD2_N	51	DP Lane 2-	Output
10	DP0_TXD3_P	59	DP Lane 3+	Output
11	_	-	Ground	Ground
12	DP0_TXD3_N	57	DP Lane 3-	Output

Pin#	Module Pin Name	Module Pin #	Usage/Description	Type/Dir
13	_	_	MODE to support Dual-role mode. Connects from DP connector to PI3AUX221ZTAEX device to select between DP or HDMI mode.	Input
14	_	_	CEC_DP: Not used – pulled to GND through 1 Mohm resistor	Unused
15	DP0_AUX_N	90	DisplayPort Auxiliary Channel 0-	Bidir
16	_	_	Ground	Ground
17	DP0_AUX_P	92	DisplayPort Auxiliary Channel 0+	Bidir
18	DP0_HPD	88	HDMI™ Hot Plug Detect	Input
19	_	_	Power Return (Ground)	Ground
20	_	_	+3.3 V	Power

Note: In the Type/Dir column, Output is to DP connector. Input is from DP connector. Bidir is for bidirectional signals.

Legend Ground	Power	Reserved
----------------------	-------	----------

2.4 M.2 Key E Expansion Slot

The Jetson Orin Nano carrier board includes a M.2, Key E Slot Mini-PCIe Expansion slot (J10). This includes interface options for WiFi/BT including PCIe (x1), USB 2.0, UART, I2S, and I2C optional.



- > The Jetson Orin Nano Developer Kit carrier board will only support single sided M.2 Key E modules.
- > Stuffing resistors for connecting I2C2 to pins 58 and 60 of the M.2 Key E connector are not installed by default. If I2C is required, 0Ω resistors can be installed at locations R106 and R107. Care should be taken as some M.2 cards can cause conflicts with other devices connected to the I2C interface.

Table 2-0. WILL NEV L EXPANSION SIOCE IN DESCRIPTION - 3 TO	Table 2-6.	M.2 Key E Expansion Slot Pin Description – J	10
---	------------	--	----

Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir	Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir
1	-		Ground	Ground		-	_	No Pin	_
3	USB2_D_P	123			2				
5	USB2_D_N	121	USB 2.0 Data	Bidir	4	-	_	Main 3.3V Supply	Power
7	-		Ground	Ground	6	-	_	Unused	Unused
9	-	_	Unused	Unused	8	I2S1_CLK	226	I2S #1 Clock	Bidir, 1.8V

Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir	Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir
11					10	12S1_FS	224	I2S #1 Left/Right Clock	Bidir, 1.8V
13	-				12	I2S1_DIN	222	I2S #1 Data In	Input, 1.8V
15				14	I2S1_DOUT	220	I2S #1 Data Out	Bidir, 1.8V	
17					16	-	-	Unused	Unused
19					18	-	_	Ground	Ground
21					20	GPIO02	124	Bluetooth #2 Wake AP	Input, 3.3V
23					22	UARTO_RXD	101	UART #0 Receive	Input, 1.8V
25	_				24				
27	-			l la cara d	26				l lava a al
29	_	_	Key	Unused	28	_	_	Key	Unused
31					30				
33	-	-	Ground	Ground	32	UARTO_TXD	99	UART #0 Transmit	Output, 1.8V
35	PEX1_TX0_P	174	PCIe #1 Transmit		34	UARTO_CTS*	105	UART #0 Clear to Send	Input, 1.8V
37	PEX1_TX0_N	172	Lane 0	Output	36	UARTO_RTS*	103	UART #0 Request to Send	Output,
39	_	-	Ground	Ground	38				
41	PEX1_RX0_P	169	PCIe #1 Receive Lane		40				
43	PEX1_RX0_N	167	0	Input	42			Llava ad	Llavasal
45	-	-	Ground	Ground	44	-	_	Unused	Unused
47	PEX1_CLK_P	175	PCIe #1 Reference	Output	46				
49	PEX1_CLK_N	173	clock	Output	48				
51	-	-	Ground	Ground	50	CLK_32K_OUT	210	Suspend Clock (32 KHz)	Output, 3.3V
53	PEX1_CLKRE Q*	182	PCIe #1 Clock Request	Bidir, 3.3V	52	PEXO_RST*	183	PCIe #0 Reset	Output, 3.3V
55	PEX_WAKE*	179	PCIe Wake	Input, 3.3V	54	GPIO3	126	BT Enable	Output, 3.3V
57	-	-	Ground	Ground	56	GPIO5	128	Wi-Fi Disable	Output, 3.3V
59					58	I2C2_SDA	234	General I2C #2	Bidir/OD,
61	-		Unused	Unused	60	I2C2_SCL	232	(optional)	1.8V
63	-	-	Ground	Ground	62	GPIO10	212	M.2, Key E Connector Alert	Input, 1.8V

Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir	Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir
65					64				
67	-	-	Unused	Unused	66				
69	_	_	Ground	Ground	68	-	-	Unused	Unused
71					70				
73	-	-	Unused	Unused	72				
75	_	_	Ground	Ground	74	-	-	Main 3.3V Supply	Power

Note: In the Type/Dir column, Output is to M.2 module. Input is from M.2 module. Bidir is for bidirectional signals.

Legend	Ground	Power	Reserved
--------	--------	-------	----------

2.5 M.2 Key M Expansion Slot

The carrier board includes two M.2, Key M Slots for NVMe storage (J11 and J24). The M.2, Key M slot J11 supports PCIe (x4), Gen4. The M.2, Key M slot J24 supports PCIe (x2), Gen4.



- > Jetson Orin Nano modules supports only up to Gen3 PCIe, and Jetson Orin NX modules support up
- > The Jetson Orin Nano Developer Kit carrier board will only support single sided M.2 Key M modules.

Table 2-7. M.2 Key M Expansion Slot Pin Description - J11 (x4 PCle)

Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir Default	Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir Default
1					2				
3	-	_	Ground	Ground	4	-	-	Main 3.3V Supply	Power
5	PCIEO_RX3_N	155	PCIe IF #0 Lane 3		6				
7	PCIEO_RX3_P	157	Receive	Input	8	-	_	Unused	Unused
9	-	_	Ground	Ground	10				
11	PCIEO_TX3_N	154	PCIe IF #0 Lane 3		12				
13	PCIEO_TX3_P	156	Transmit	Output	14				
15	-	-	Ground	Ground	16	_	_	Main 3.3V Supply	Power
17	PCIEO_RX2_N	149	PCIe IF #0 Lane 2		18				
19	PCIEO_RX2_P	151	Receive	Input	20	-	-	Unused	Unused

Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir Default	Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir Default	
21	-	_	Ground	Ground	22					
23	PCIEO_TX2_N	148	PCIe IF #0 Lane 2		24					
25	PCIE0_TX2_P	150	Transmit	Output	26					
27	-	-	Ground	Ground	28					
29	PCIEO_RX1_N	137	PCIe IF #0 Lane 1		30					
31	PCIEO_RX1_P	139	Receive	Input	32					
33	-	_	Ground	Ground	34					
35	PCIEO_TX1_N	140	PCIe IF #0 Lane 1	_	36					
37	PCIEO_TX1_P	142	Transmit	Output	38					
39	-	_	Ground	Ground	40					
41	PCIEO_RXO_N	131	PCIe IF #0 Lane 0		42]-	-	Unused	Unused	
43	PCIEO_RXO_P	133	Receive	Input	44	GPIO10	212	M.2 Key M Alert	Input, 1.8V	
45	-	_	Ground	Ground	46				Unused	
47	PCIEO_TXO_N	134			48	-	_	Unused		
49	PCIEO_TXO_P	136	PCIe IF #0 Lane 0 Transmit	Output	50	PEXO_RST*	181	PCIe IF #0 Reset	Output, 3.3V	
51	-	-	Ground	Ground	52	PEXO_ CLKREQ*	180	PCIe IF #0 Clock Request	Input, 3.3V	
53	PCIEO_CLK_N	160	PCIe IF #0 Reference Clock	Output	54	PEX_WAKE*	179	PCIe Wake (Level Shifted from 3.3V to 1.8V)	Input, 3.3V	
55	PCIEO_CLK_P	162			56					
57	-	-	Ground	Ground	58		_	Unused	Unused	
59					60	-				
61					62	_			lle eed	
63	_		Unused (Key)	Unused	64	_		Unused (Key)	Unused	
65					66					
67	_	_	Unused	Unused	68	-	_	32 KHz Suspend Clock	Output, 3.3V	
69					70					
71				72	-	_	Main 3.3V Supply	Power		
73	-			74						
75								No Pin	_	

Note: In the Type/Dir column, Output is to M.2 module. Input is from M.2 Module. Bidir is for bidirectional signals.

Legend	Ground	Power	Reserved

M.2 Key M Expansion Slot Pin Description - J24 (x2 PCle) Table 2-8.

Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir Default	Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir Default
1					2				
3	-	-	Ground	Ground	4			Main 3.3V Supply	Power
5					6				
7	-	-	Unused	Unused	8	-	_	Unused	Unused
9	-	-	Ground	Ground	10				
11					12				
13	-	-	Unused	Unused	14				
15	-	-	Ground	Ground	16	-	-	Main 3.3V Supply	Power
17					18				
19	-	-	Unused	Unused	20				
21	-	-	Ground	Ground	22				
23					24				
25	-	-	Unused	Unused	26				
27	-	-	Ground	Ground	28				
29	PCIE2_RX1_N	58	PCIe IF #2 Lane 1		30				
31	PCIE2_RX1_P	60	Receive	Input	32			Unused	Unused
33	-	_	Ground	Ground	34				
35	PCIE2_TX1_N	64	PCIe IF #2 Lane 1		36				
37	PCIE2_TX1_P	66	Transmit	Output	38				
39	-	_	Ground	Ground	40				
41	PCIE2_RX0_N	40	PCIe IF #2 Lane 0		42				
43	PCIE2_RX0_P	42	Receive	Input	44	GPIO10	212	M.2 Key M Alert	Input, 1.8V
45	-	_	Ground	Ground	46				
47	PCIE2_TX0_N	46	50, 15 #0 .		48	-	_	Unused	Unused
49	PCIE2_TX0_P	48	PCIe IF #2 Lane 0 Transmit	Output	50	PEX2_RST*	219	PCIe IF #0 Reset	Output, 3.3V
51	_	_	Ground	Ground	52	PEX2_CLKREQ	221	PCIe IF #0 Clock Request	Input, 3.3V
53	PCIE2_CLK_N	52	PCIe IF #2 Reference Clock	Output	54	PEX_WAKE*	179	PCIe Wake (Level Shifted from 3.3V to 1.8V)	Input, 3.3V
55	PCIE2_CLK_P	54			56				
57	-	-	Ground	Ground	58	-		Unused	Unused
59	_	-	Unused (Key)	Unused	60	_	_	Unused (Key)	Unused

Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir Default	Pin#	Module Pin Name	Module Pin#	Usage/Description	Type/Dir Default
61					62				
63					64				
65					66				
67	_	_	Unused	Unused	68	_	_	32 KHz Suspend Clock	Output, 3.3V
69					70				
71					72	_	_	Main 3.3V Supply	Power
73	_	_	Ground	Ground	74				
75							-	–No Pin	_

- 1. PCle 2 module pin names are using the Orin NX and Orin Nano function names.
- 2. In the Type/Dir column, Output is to M.2 module. Input is from M.2 Module. Bidir is for bidirectional signals.

Legend Ground	Power	Reserved
----------------------	-------	----------

Chapter 3. Carrier Board Custom Expansion IF Connections

The Jetson Orin Nano carrier board supports several expansion headers and connectors that have custom pinouts. The following lists the headers and connectors that have custom pinouts.

- > Jetson Orin Nano Module Connector, 260-pin, SO-DIMM, 1.27 mm pitch
- > Camera Connectors (x2), 22 position, Flex Connector, 0.5 mm pitch
- 40-Pin Expansion Header, 2x20, 2.54 mm pitch
- Button Header, 2x4, 2.54 mm pitch
- > Optional CAN Bus header
- > Fan Connector, 4-pin, 1.25 mm pitch
- > Optional real-time-clock (RTC) back-up connector
- > DC Power Jack
- > Optional Power-over Ethernet (PoE) header, 1x4, 2.54 mm pitch
- Optional PoE backpower header, 1x, 2.54 mm pitch

Jetson Orin Nano Module Connector 3.1

The carrier board interfaces to the Jetson Orin Nano module using a 260-pin SODIMM connector (J2). The carrier board has a TE Connectivity 2309413-1 connector. This interfaces with the Jetson Orin Nano edge fingers. The connector pinout can be found in the Jetson Orin Nano Product Design Guide.

Camera Connector 3.2

The Jetson Orin Nano carrier board includes two 22-position flex (0.5 mm pitch) camera connectors (J20 and J219). The connector used on the carrier board is a Molex Japan Part #54548-2272.

The connectors support the following.

- > J20: CSI 1 x2 lane
- > J21: CSI 1 x2 lane or 1 x4 lane
- > Both J20/J21: C
 - CAM_I2C, clock, and control GPIOs for the camera
 - 3.3V Supply

Table 3-1. Camera #0 Connector Pin Description - J20

Pin#	Module Pin Name	Module Pin #	Usage/Description	Type/Dir	
1	_	_	+3.3V	Power	
2	CAM_I2C_SDA	215	Camera I2C. 2.2 kΩ pull-ups on module. The module CAM_I2C	Bidir, 3.3V	
3	CAM_I2C_SCL	213	pins connect to an I2C mux. The camera connector #0 (J20) receives the I2C from the mux (first output). The I2C signals on the camera side of the mux have 1 k Ω pull-ups.	Output, 3.3V	
4	_	_	Ground	Ground	
5	CAMO_MCLK	116	Camera #0 Primary Clock	Output, 1.8V	
6	CAMO_PWDN	114	Camera #0 Power-down	Output, 1.8V	
7	_	_	Ground	Ground	
8	CSIO_D1_P	18	CCLO Data 1	la accet	
9	CSIO_D1_N	16	CSI 0 Data 1	Input	
10	_	_	Ground	Ground	
11	CSIO_DO_P	6	CSI 0 Data 0	lagut	
12	CSIO_DO_N	4	CSI O Data O	Input	
13	_	-	Ground	Ground	
14	CSI1_CLK_P	11	CSI 0 Clock	lagut	
15	CSI1_CLK_N	9	CSI O Clock	Input	
16	_	_	Ground	Ground	
17	CSI1_D1_P	17	CSI 1 Data 1	lagut	
18	CSI1_D1_N	15	CSI I Data I	Input	
19	-	-	Ground	Ground	
20	CSI1_D0_P	5	CSUL Data O	Innut	
21	CSI1_D0_N	3	CSI 1 Data 0	Input	
22	_	_	Ground	Ground	

Note: In the Type/Dir column, Output is to camera module. Input is from camera module. Bidir is for bidirectional signals.

Legend	Ground	Power	Reserved
--------	--------	-------	----------

Camera #1 Connector Pin Description - J21 Table 3-2.

Pin#	Module Pin Name	Module Pin #	Usage/Description	Type/Dir	
1	_	_	+3.3V	Power	
2	CAM_I2C_SDA	215	Camera I2C. 2.2 $k\Omega$ pull-ups on module. The module CAM_I2C	Bidir, 3.3V	
3	CAM_I2C_SCL	213	pins connect to an I2C mux. The camera connector #1 (J21) receives the I2C from the mux (second output). The I2C signals on the camera side of the mux have 1 k Ω pull-ups.	Output, 3.3V	
4	_	_	Ground	Ground	
5	CAM1_MCLK	122	Camera #0 Primary Clock	Output, 1.8V	
6	CAM1_PWDN	120	Camera #0 Power-down	Output, 1.8V	
7	_	_	Ground	Ground	
8	CSI3_D1_P	35	001.2 Data 1	l t	
9	CSI3_D1_N	33	CSI 3 Data 1	Input	
10	_	_	Ground	Ground	
11	CSI3_D0_P	23	CSI 3 Data 0	lnnut	
12	CSI3_D0_N	21	CSI 3 Data 0	Input	
13	_	-	Ground	Ground	
14	CSI2_CLK_P	30	- CCL 2 Closel	loout	
15	CSI2_CLK_N	28	CSI 2 Clock	Input	
16	_	-	Ground	Ground	
17	CSI2_D1_P	36	- CCL 2 Data 1	la a cot	
18	CSI2_D1_N	34	CSI 2 Data 1	Input	
19	_	-	Ground	Ground	
20	CSI2_D0_P	24	CSI 2 Data 0	Innut	
21	CSI2_D0_N	22	C3I 2 Data 0	Input	
22	-	_	Ground	Ground	

Note: In the Type/Dir column, Output is to camera module. Input is from camera module. Bidir is for bidirectional signals.

Legend	Ground	Power	Reserved
_090	Oroana	1 011 01	1 COCI VCG

40-Pin Expansion Header 3.3

The Jetson Orin Nano carrier board includes a 40-pin (2x20, 2.54 mm pitch) expansion header (J12). The connector used on the carrier board is an Astron Technology (Part # 27-0169H-220-1G-H).

The expansion connector includes various audio and control interfaces including:

- > I2S
- > Audio (AU) clock
- > 12C (x2)
- > SPI (x2)
- > UART
- > GPIOs (x3 See notes)



- All the signals on the expansion header use 3.3V levels.
- All the interface signal pins (I2S, I2C, SPI, UART, and AU clock) can also be configured as GPIOs.
- > Any pull-up or pull-down resistors on the signals (except I2C) must be weak (limited to $>50 k\Omega$).



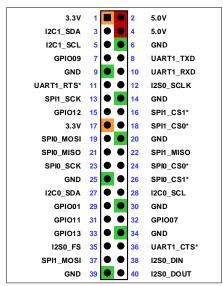


Table 3-3. Expansion Header Pin Description – J12

Header Pin#	Module Pin Name	Module Pin#	SoC Pin Name	Default Usage / Description	Alternate Functionality	Type/ Dir	Pin Drive or Power Pin Max Current	SoC GPIO Port#	Power- on Default	PU/PD on Module	Notes
1	-	-	-	Main 3.3V Supply	-	Power (input)	1A	-	_	_	1
2	-	-	-	Main 5.0V Supply	-	Power (input/outpu t_	1A	-	-	-	1
3	I2C1_SDA	191	GP16_I2C8_DAT	I2C#1 Data	_	Bidir OD	±2 mA	PDD.02	z	2.2ΚΩ PU	2
4	-	_	_	Main 5.0V Supply	_	Power	1A	-	-	_	_
5	I2C1_SCL	189	GP15_I2C8_CLK	I2C#1 Clock	_	Bidir OD	±2 mA	PDD.01	z	2.2ΚΩ PU	2
6	-	-	-	Ground	-	Ground	-	-	-	_	-
7	GPIO09	211	GP167	GPIO	Audio Primary Clock	Bidir/Output	±20uA	PAC.06	pd		3
8	UART1_TXD	203	GP70_UART1_T XD_BOOT2_STR AP	UART#1 Transmit	GPIO	Output/Bidir	±20uA	PR.02	pd		3
9	_	-	_	Ground	_	Ground	-	-	-	_	_
10	UART1_RXD	205	GP71_UART1_R XD	UART#1 Receive	GPIO	Input/Bidir	±20uA	PR.03	pd		3
11	UART1_RTS*	207	GP72_UART1_ RTS_N	GPIO	UART #2 Request to Send	Bidir/Output	±20uA	PR.04	pd		3
12	I2SO_SCLK	199	GP122	GPIO	Audio I2S #0 Clock	Bidir	±20uA	PH.07	pd		3
13	SPI1_SCK	106	GP36_SPI3_CLK	GPIO	SPI #1 Shift Clock	Bidir/Output	±20uA	PY.00	pd		3
14	-	-	-	Ground	-	Ground	-	-	-	_	-
15	GPIO12	218	GP88_PWM1	GPIO	_	Bidir	±20uA	PN.01	z		3
16	SPI1_CSI1*	112	GP40_SPI3_CS1 _N	GPIO	SPI #1 Chip Select #1	Bidir/Output	±20uA	PY.04	z		3
17	-	-	-	Main 3.3V Supply	-	Power	1A	-	-	-	1
18	SPI1_CSI0*	110	GP39_SPI3_CS0 _N	GPIO	SPI #0 Chip Select #0	Bidir/Output	±20uA	PZ.06	z		3
19	SPI0_MOSI	89	GP49_SPI1_MO	GPIO	SPI #0 Primary Out/Secondary In	Bidir/Output	±20uA	PZ.05	pd		3
20	-	-	-	Ground	-	Ground	-	-	-	-	-
21	SPI0_MISO	93	GP48_SPI1_MIS	GPIO	SPI #0 Primary In/Secondary Out	Bidir/Input	±20uA	PZ.04	pd		3
22	SPI1_MISO	108	GP37_SPI3_MIS	GPIO	SPI #1 Primary In/Secondary Out	Bidir/Input	±20uA	PY.01	pd		3
23	SPIO_SCK	91	GP47_SPI1_CLK	GPIO	SPI #0 Shift Clock	Bidir/Output	±20uA	PZ.03	pd		3

Header Pin#	Module Pin Name	Module Pin#	SoC Pin Name	Default Usage / Description	Alternate Functionality	Type/ Dir	Pin Drive or Power Pin Max Current	SoC GPIO Port#	Power- on Default	PU/PD on Module	Notes
24	SPI0_CS0*	95	GP50_SPI1_CS0 _N	GPIO	SPI #0 Chip Select #0	Bidir/Output	±20uA	PZ.06	z		3
25	_	-	_	Ground	_	Ground	_	_	-	_	_
26	SPIO_CS1*	97	GP51_SPI1_CS1	GPIO	SPI #0 Chip Select #1	Bidir/Output	±20uA	PZ.07	pu		3
27	I2CO_SDA	187	GP14_I2C2_DAT	12C #0 Data	GPIO	Bidir OD/Bidir	±2 mA	PDD.00	z	1.5ΚΩ PU	2
28	I2CO_SCL	185	GP13_I2C2_CLK	I2C #0 Clock	GPIO	Bidir OD/Bidir	±2 mA	PCC.07	z	1.5ΚΩ PU	2
29	GPI001	118	GP65	GPIO	General Purpose Clock #0	Bidir/Output	±20uA	PQ.05	pd		3
30	_	-	_	Ground	_	Ground	_	_	_	-	_
31	GPIO11	216	GP66	GPIO	General Purpose Clock #1	Bidir/Output	±20uA	PQ.06	pd		3
32	GPIO07	206	GP113_PWM7	GPIO	PWM	Bidir/Output	±20uA	PG.06	z		3
33	GPIO13	228	GP115	GPIO	PWM	Bidir/Output	±20uA	PH.00	z		3
34	_	-	_	Ground	_	Ground	_	_	-	_	_
35	12S0_FS	197	GP125	GPIO	Audio I2S #0 Field Select	Bidir	±20uA	PI.02	pd		3
36	UART1_CTS*	209	GP73_UART1_ CTS_N	GPIO	UART #1 Clear to Send	Bidir/Input	±20uA	PR.05	pd		3
37	SPI1_MOSI	104	GP38_SPI3_MO	GPIO	SPI #1 Primary Out/Secondary In	Bidir/Output	±20uA	PY.02	pd		3
38	I2SO_DIN	195	GP124	GPIO	Audio I2S #0 Data in	Bidir/Input	±20uA	PI.01	pd		3
39	-	-	-	Ground	_	Ground	-	-	-	-	-
40	I2SO_DOUT	193	GP123	GPIO	Audio I2S #0 Data Out	Bidir/Output	±20uA	PI.00	pd		3

- 1. This is current capability per power pin.
- 2. These pins are connected to the SoC directly. They are open-drain (either pulled up or driven low by the SoC when configured as outputs). The max drive that meets the data sheet VOL is ±2 mA.
- 3. These pins connect to TI TXB0108 level translators. Due to the design of these devices, the output drivers are very weak, so they can be overdriven by another connected device output for bidirectional support.
- 4. In the Type/Dir column, output is to expansion header. Input is from expansion header. Bidir is for bidirectional signals. Where two directions are shown, the first is for the primary function (mostly GPIOs) and the second is for the alternate function.
- 5. Where the signal direction is input or output in this table (Table 3-3), this matches the typical special function usage (for example, SPI, I2S, and so on). The direction is bidirectional if these are configured as GPIOs.
- 6. All signals on the 40-pin header are 3.3V levels.

Legend	Ground	Power	Reserved
Legena	Ground	Power	Reserved

Button Header 3.4

The Jetson Orin Nano carrier board brings several system signals (power, reset, and force recovery), UART, and Sleep/Wake LED-related signals to a pair of standard 0.254 mm pitch header. The button header is J14.

Table 3-4. Button Header Description - J14

Pin #	Module Pin Name	Module Pin #	Usage/Description	Type/Dir Default
1	-	_	PC_LED-: Connects to LED Cathode to indicate System Sleep/Wake (Off when system in sleep mode)	Input, 5V
2	_	_	PC_LED+: Connects to LED Anode (see Pin 1)	Output
3	UART2_RXD (DEBUG)	238	UART #2 Receive	Input, 3.3V
4	UART2_TXD (DEBUG)	236	UART #2 Transmit	Output, 3.3V
5	_	_	AC OK: Connect pins 5 and 6 to disable Auto-Power-On and require power button press.	Input, 3.3V
6	-	_	Auto Power-on disable: Pulled to GND. See Pin 5.	Not applicable
7	_	_	Ground	Ground
8	SYS_RESET*	239	Temporarily connect pins 7 and 8 to reset system	Input, 1.8V
9	_	_	Ground	Ground
10	FORCE_RECOVERY*	214	Connect pins 9 and 10 during power-on to put system in USB Force Recovery mode.	Input, 1.8V
11	-	_	Ground	Ground
12	SLEEP/WAKE*	240	Connect pins 11 and 12 to initiate power-on if Auto-Power- On disabled (Pins 5 and 6 connected).	Input, 5V

Note: In the Type/Dir column, Output is to button header. Input is from button header. Bidir is for bidirectional signals.

Legend Ground Power Reserved	
------------------------------	--

3.5 Optional CAN Bus Header

The Jetson Orin Nano carrier board includes the footprint for a 4-pin, 2.45 mm pitch header (J17) which supports a CAN bus interface.

Table 3-5. Optional CAN Header Pin Description - J17

Pin#	Module Pin Name	Module Pin #	Usage/Description	Type/Dir Default
1	CAN_TX	145	CAN Bus transmit	Output, 3.3V
2	CAN_RX	143	CAN Bus receive	Input, 3.3V
3	_	_	Ground	Ground
4	-	_	Main 3.3V Supply	Power

Note: In the Type/Dir column, Output is to CAN connector. Input is from CAN connector. Bidir is for bidirectional signals.



Fan Connector 36

The Jetson Orin Nano carrier board includes a 4-pin fan header (J13). The connector used is a Singatron Enterprise Co., Ltd., Part # 2WBA2542WVC-F-04PNLBT1N00G.

Table 3-6. Fan Connector Pin Description - J13

Pin#	Module Pin Name	Module Pin #	Usage/Description	Type/Dir Default
1	_	_	Ground	Ground
2	-	-	Main 5.0V Supply	Power
3	GPIO08	208	Fan Tachometer signal	Input, 5V
4	GPIO14	230	Fan Pulse Width Modulation signal	Output, 5V

Note: In the Type/Dir column, Output is to fan connector. Input is from fan connector. Bidir is for bidirectional signals.

Legend	Ground	Power	Reserved
5	Oi oana	1 01101	110001100

3.7 Optional Battery Back-up Coin Cell Holder

The Jetson carrier board has a connector where an RTC backup battery can be connected. This connector (J3) is commonly used on laptop designs. The connector used is a Wieson Technologies AC2651-0011-003-HH, 2-pin, 1.25 mm pitch connector.

Table 3-7. RTC Backup Batter Connector Pin Description – J3

Pin#	Associated Module Pin Name	Module Pin #	Usage/Description	Type/Dir
1	PM IC_BBAT	235	RTC backup battery supply	Power
2	-	_	Ground	Ground

Legend Ground	Power	Reserved
----------------------	-------	----------

DC Power Jack 3.8

The Jetson Orin Nano carrier board uses a DC power jack (J16) to bring in the power from the included DC power supply. The jack used on the carrier board is a Singatron Enterprise part (part #: 2DC-0005D206F). The mating barrel jack connector dimensions are:

- > Barrel length: 9.5 mm
- Barrel diameter: 5.5 mm
- Pin receptacle: Accepts 2.5 mm jack pin
- The center pin is positive (+V)
- Max current supported is 3.5 A

Figure 3-2. **Jack Connector**

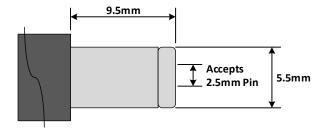


Table 3-8. DC Jack Pin Description - J16

Pin#	Module Pin Name	Module Pin #	Usage/Description			Type/Dir Default
1	_	_	Main DC in	nput supplying DC jack input (9-20 V)		Power
2	_	_	Ground			Ground
3	_	_	Ground	Ground		Ground
Legend	Ground	Pov	wer	Reserved		

Optional Power-Over Ethernet and 3.9 **Backpower Headers**

The Jetson Orin Nano carrier board provides an option for an alternate main power input (besides the DC power jack). A 4-pin Power over Ethernet (PoE) header (J19 – 1x4 male, 2.54 mm pitch) brings out the VC power pins of the Ethernet connector. In addition, a 2pin Backpower header (J18 - 1x2 male, 2.54 mm pitch) provides an alternate path for the input voltage (3 A max). To use this alternate PoE power mechanism, the design will require a power converter to take the high-voltage PoE supply (38 V-60 V) and convert it to the 5 V-20 V input the carrier board requires.

Figure 3-3. **PoE Alternative Power Input**

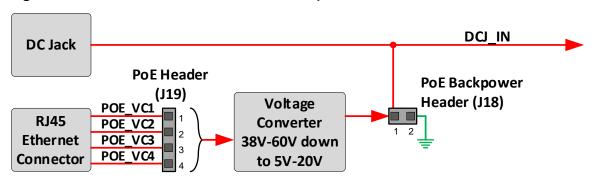


Table 3-9. PoE Header - J19

Pin#	Module Pin Name	Module Pin #	Usage/De	scription		Type/Dir Default
1	_	_	Ethernet R	G45 connector PoE VC1	power	Power
2	_	_	Ethernet R	G45 connector PoE VC2	power	Power
3	-	_		Ethernet RG45 connector PoE VC3 power		Power
4	_	_	Ethernet RG45 connector PoE VC4 power		power	Power
					1	
Legend	Ground	Pov	wer	Reserved		

Table 3-10. PoE Backpower Header – J18

Pin #	Module Pin Name	Module Pin #	Usage/Description	Type/Dir Default
1	_	_	Main DC input supplying DC jack input (9 V-20 V). 3 A max.	Power
2	_	_	Ground	Ground

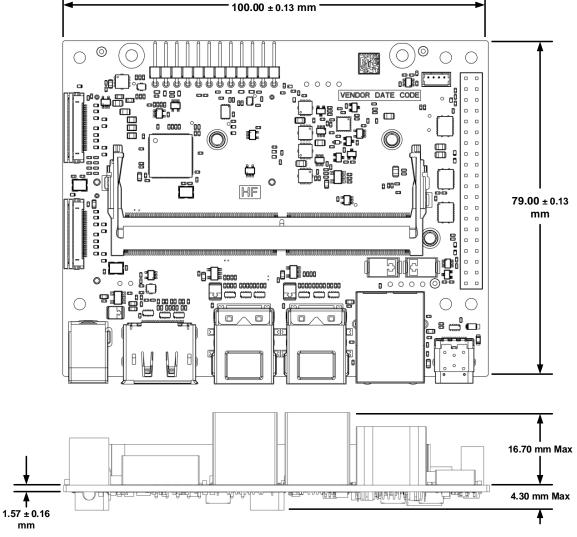
Legend Ground	Power	Reserved
----------------------	-------	----------

Chapter 4. Mechanical Specification

Figure 4-1 and Figure 4-2 show the mechanical dimensions for the carrier board and the developer kit.

The Developer Kit Weighs 0.175kg

Figure 4-1. **Developer Kit Carrier Board Mechanical Dimensions** 100.00 ± 0.13 mm



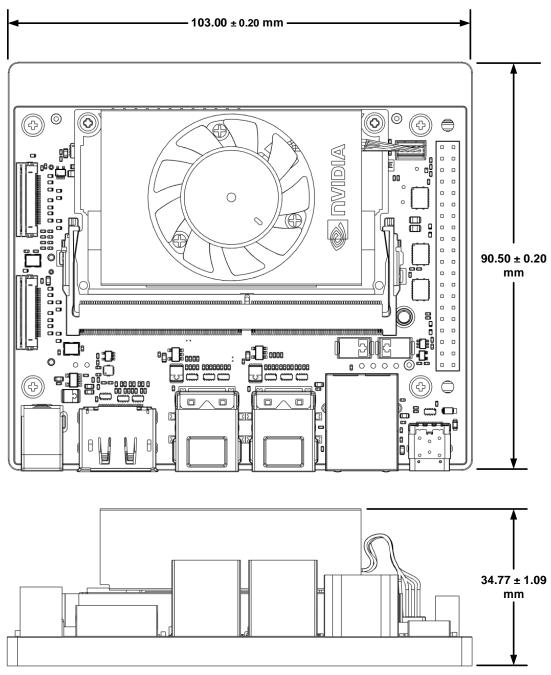


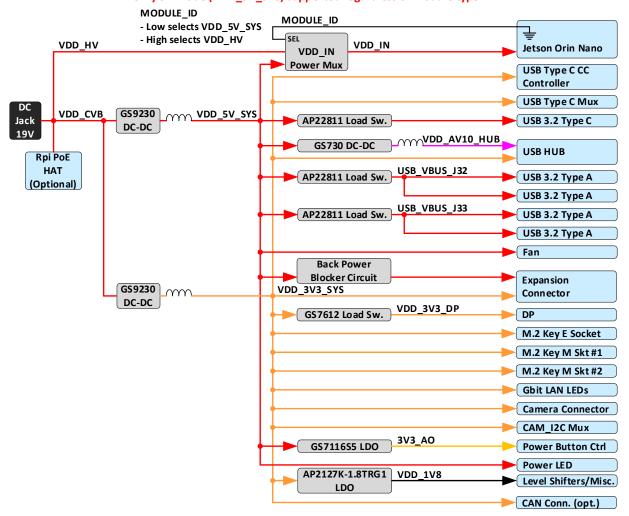
Figure 4-2. **Developer Kit Mechanical Dimensions**

Chapter 5. Interface Power

Figure 5 1 shows the power diagram.

Figure 5-1. **Power Diagram**

Note: Jetson Orin Nano DevKit Carrier Board has pull-up on MODULE_ID removed. Only 5V mode (VDD_5V_SYS) supported regardless of module type.



The following tables show the allocation of supplies to the connectors on the Jetson Orin Nano carrier board and current capabilities.

Interface Power Supply Allocation Table 5-1.

Power Rails	Usage	(V)	Power Supply or Gate	Source	Enable
DC_IN	Main power input from DC Adapter	19.5	AONR21357025 Power mux	DC Adapter	
VDD_5V_SYS	Main 5.0V supply	5.0	GS9230NVTQ-R	VDD_CVB (DC_IN after Power FET)	VDD_CVB
VDD_3V3_SYS	Main 3.3V supply	3.3	GS9230NVTQ-R	VDD_CVB	SYS_RESET_IN*
3V3_AO	Button MCU	3.3	GS7116S5-ADJ-R LDO	VDD_5V_SYS	VDD_5V_SYS regulator power good
VDD_1V8	Main 1.8V supply	1.8	AP2127K-1.8TRG1	VDD_3V3_SYS	3.3V_IO_PG
VDD_AV10_HUB	USB hub	1.1	GS7303ACTD-R	VDD_5V_SYS	VDD_3V3_SYS regulator power good
USBC_VBUS	5V VBUS for USB Type C connector	5.0	AP22811AW5-7	VDD_5V_SYS	ID from USB Type C CC controller
USB_VBUS_A	5V VBUS for dual stacked 3.0 Type A connector	5.0	AP22811AW5-7 Load Switch	VDD_5V_SYS	From USB Hub
USB_VBUS_B	5V VBUS for dual stacked 3.0 Type A connector	5.0	AP22811AW5-7 Load Switch	VDD_5V_SYS	From USB Hub
VDD_3V3_DP	3.3V rail for DP connector	5.0	GS7612S5MC-R Load Switch	VDD_3V3_SYS	VDD_3V3_SYS regulator power good

Interface Supply Current Capabilities Table 5-2.

Power Rails	Usage	(V)	Max Current (A)
DCJ_IN	Main power input from DC Adapter	19.0	4.2
VDD_5V_SYS	Main 5.0V supply	5.0	7.8
VDD_3V3_SYS	Main 3.3V supply	3.3	5.4
VDD_1V8	Main 1.8V supply	1.8	0.0002
3V3_AO	3.3V Always-on supply	3.3	0.200

Supply Current Capabilities per Connector per Supply Table 5-3.

Power Rails	Connector	(V)	Max Current (A)
VDD_5V_SYS	SO-DIMM (VDD_IN)	5.0	5.0
	40-pin header		0.5
	Fan connector		0.15
VDD_3V3_DP	DP connector		0.5
USBC_VBUS	USB Type C		0.5
USB_VBUS_A/B	USB 3.2 type A (x4)		0.5
VDD_3V3_SYS	40-pin header	3.3	0.1
	M.2 Key E socket		0.8
	M.2 Key M sockets (x2)		2.1
	Camera connectors (x2)		0.26

Notice

This document is provided for information purposes only and shall not be regarded as a warranty of a certain functionality, condition, or quality of a product. NVIDIA Corporation ("NVIDIA") makes no representations or warranties, expressed or implied, as to the accuracy or completeness of the information contained in this document and assumes no responsibility for any errors contained herein. NVIDIA shall have no liability for the consequences or use of such information or for any infringement of patents or other rights of third parties that may result from its use. This document is not a commitment to develop, release, or deliver any Material (defined below), code, or functionality.

NVIDIA reserves the right to make corrections, modifications, enhancements, improvements, and any other changes to this document, at any time without notice.

Customer should obtain the latest relevant information before placing orders and should verify that such information is current and complete. NVIDIA products are sold subject to the NVIDIA standard terms and conditions of sale supplied at the time of order acknowledgement, unless otherwise agreed in an individual sales agreement signed by authorized representatives of NVIDIA and customer ("Terms of Sale"). NVIDIA hereby expressly objects to applying any customer general terms and conditions with regards to the purchase of the NVIDIA product referenced in this document. No contractual obligations are formed either directly or indirectly by this document.

Unless specifically agreed to in writing by NVIDIA, NVIDIA products are not designed, authorized, or warranted to be suitable for use in medical, military, aircraft, space, or life support equipment, nor in applications where failure or malfunction of the NVIDIA product can reasonably be expected to result in personal injury, death, or property or environmental damage. NVIDIA accepts no liability for inclusion and/or use of NVIDIA products in such equipment or applications and therefore such inclusion and/or use is at customer's own risk.

NVIDIA makes no representation or warranty that products based on this document will be suitable for any specified use. Testing of all parameters of each product is not necessarily performed by NVIDIA. It is customer's sole responsibility to evaluate and determine the applicability of any information contained in this document, ensure the product is suitable and fit for the application planned by customer, and perform the necessary testing for the application in order to avoid a default of the application or the product. Weaknesses in customer's product designs may affect the quality and reliability of the NVIDIA product and may result in additional or different conditions and/or requirements beyond those contained in this document. NVIDIA accepts no liability related to any default, damage, costs, or problem which may be based on or attributable to: (i) the use of the NVIDIA product in any manner that is contrary to this document or (ii) customer product designs.

No license, either expressed or implied, is granted under any NVIDIA patent right, copyright, or other NVIDIA intellectual property right under this document. Information published by NVIDIA regarding third-party products or services does not constitute a license from NVIDIA to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property rights of the third party, or a license from NVIDIA under the patents or other intellectual property rights of NVIDIA

Reproduction of information in this document is permissible only if approved in advance by NVIDIA in writing, reproduced without alteration and in full compliance with all applicable export laws and regulations, and accompanied by all associated conditions, limitations, and notices. THIS DOCUMENT AND ALL NVIDIA DESIGN SPECIFICATIONS, REFERENCE BOARDS, FILES, DRAWINGS, DIAGNOSTICS, LISTS, AND OTHER DOCUMENTS (TOGETHER AND SEPARATELY, "MATERIALS") ARE BEING PROVIDED "AS IS." NVIDIA MAKES NO WARRANTIES, EXPRESSED, IMPLIED, STATUTORY, OR OTHERWISE WITH RESPECT TO THE MATERIALS, AND EXPRESSLY DISCLAIMS ALL IMPLIED WARRANTIES OF NONINFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE. TO THE EXTENT NOT PROHIBITED BY LAW, IN NO EVENT WILL NVIDIA BE LIABLE FOR ANY DAMAGES, INCLUDING WITHOUT LIMITATION ANY DIRECT, INDIRECT, SPECIAL, INCIDENTAL, PUNITIVE, OR CONSEQUENTIAL DAMAGES, HOWEVER CAUSED AND REGARDLESS OF THE THEORY OF LIABILITY, ARISING OUT OF ANY USE OF THIS DOCUMENT, EVEN IF NVIDIA HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. Notwithstanding any damages that customer might incur for any reason whatsoever, NVIDIA's aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms of Sale for the product.

Trademarks

NVIDIA, the NVIDIA logo, Jetson, Jetson Orin Nano, and NVIDIA Orin are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries. Other company and product names may be trademarks of the respective companies with which they are associated.

VESA DisplayPort

DisplayPort and DisplayPort Compliance Logo, DisplayPort Compliance Logo for Dual-mode Sources, and DisplayPort Compliance Logo for Active Cables are trademarks owned by the Video Electronics Standards Association in the United States and other countries.

HDMI

HDMI, the HDMI logo, and High-Definition Multimedia Interface are trademarks or registered trademarks of HDMI Licensing LLC.

Copyright

© 2023 NVIDIA Corporation. All rights reserved.

